

L Number	Hits	Search Text	DB	Time stamp
1	33	"5610442"	USPAT	2003/06/18 11:25
2	231	438/122.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:40
3	105	(438/122.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)) and (encapsulant or encapsulate or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 11:56
4	19	((438/122.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)) and (encapsulant or encapsulate or mold)) and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:39
5	40	438/124.ccls. and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 11:34
6	7	(438/124.ccls. and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (heat adj (sink or spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:07
7	4347	(chip or die) and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:06
8	233	((chip or die) and ((laser or ablate or ablatting or remove or removal) with (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (heat adj (sink or spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 11:45
9	1	257/166.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 11:55
10	193	257/666.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 11:56
11	102	(257/666.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)) and (encapsulant or encapsulate or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 11:56
12	1165	(chip or die) and ((laser or ablate or ablatting or remove or removal) near (encapsulant or encapsulate or mold)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:07
13	59	((chip or die) and ((laser or ablate or ablatting or remove or removal) near (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (heat adj (sink or spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:14
14	260	257/796.ccls. and (heat adj (sink or spreader)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:19

15	128	(laser or ablate or ablatting) near (encapsulant or encapsulate or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:52
16	88	((laser or ablate or ablatting) near (encapsulant or encapsulate or mold)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 14:32
17	27	((laser or ablate or ablatting) near (encapsulant or encapsulate or mold)) and (@ad<20000816)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:53
18	1858	(laser or ablate or ablatting) with (encapsulant or encapsulate or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:53
19	607	((laser or ablate or ablatting) with (encapsulant or encapsulate or mold)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 12:53
20	418	((laser or ablate or ablatting) with (encapsulant or encapsulate or mold)) and (chip or die)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 13:05
21	1	("6432840").PN.	USPAT	2003/06/18 13:24
22	1	("6297543").PN.	USPAT	2003/06/18 13:27
23	1	("5723900").PN.	USPAT	2003/06/18 14:14
24	1	("6544814").PN.	USPAT	2003/06/18 14:31
25	53	(laser near (watts or W)) and (Encapsualnt or encapsulate or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 14:32
26	25	((laser near (watts or W)) and (Encapsualnt or encapsulate or mold)) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 16:04
27	1	("5723900").PN.	USPAT	2003/06/18 15:54
28	1	("6297543").PN.	USPAT	2003/06/18 15:21
29	1	("6369455").PN.	USPAT	2003/06/18 16:01
31	37	(encapsulant or encapsulat) adj (heat adj (sink or dissipation or spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 16:04
32	335	(encapsulant or encapsulat) with (heat adj (sink or dissipation or spreader))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 16:04
33	223	((encapsulant or encapsulat) with (heat adj (sink or dissipation or spreader))) and (@ad<20000816)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/18 16:05